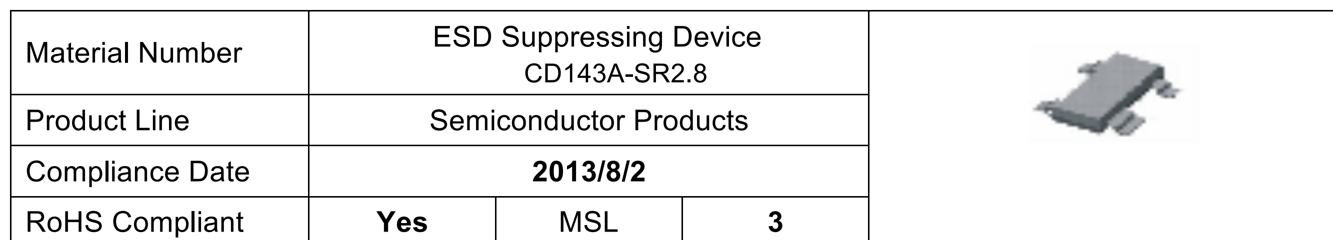
MATERIAL DECLARATION SHEET



Material Number	ESD Suppressing Device CD143A-SR2.8		
Product Line	Semiconductor Products		
Compliance Date	**2013/8/2**		
RoHS Compliant	**Yes**	MSL	**3**

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.00035	Silicon	7440-21-3	100.00%	3.16%	3.16%
2	Lead frame	Copper Alloy	0.00003	Nickel	7440-02-0	0.80%	0.28%	34.21%
			0.00005	Tin	7440-31-5	1.20%	0.42%	
			0.000003	Phosphorus	7723-14-0	0.07%	0.02%	
			0.00367	Copper	7440-50-8	96.93%	33.15%	
			0.00004	Silver	7440-22-4	1.00%	0.34%	
3	Epoxy	Polymer	0.00015	Silicon dioxide	14808-60-7	43.60%	1.35%	3.08%
			0.00009	Epoxy resin	Proprietary	25.64%	0.79%	
			0.00005	Aromatic Amine	Proprietary	15.38%	0.47%	
			0.00005	Epoxy resin modifier	Proprietary	15.38%	0.47%	
4	Cu wire	Noble metal	0.000001	Palladium	7440-05-3	2.00%	0.005%	0.25%
			0.00003	Copper	7440-50-8	98.00%	0.245%	
5	Mold Compound	Polymer	0.00519	Silica	60676-86-0	80.00%	46.83%	58.54%
			0.00065	Epoxy Resin	Trade Secret	10.00%	5.85%	
			0.00063	Phenolic Resin	Trade Secret	9.70%	5.68%	
			0.00002	Carbon Black	1333-86-4	0.30%	0.18%	

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6	Plating	plating	0.00008	Tin	7440-31-5	99.90%	0.759%	0.76%
			0.0000001	Misc., not to declare	N/A	0.10%	0.001%	
		Total weight	**0.0110803g**					

This Document was updated on: **2013/8/2**

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

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